

Application No. 10/716,729  
Response dated September 17, 2007  
to Office Action mailed May 15, 2007

**AMENDMENTS TO THE SPECIFICATION**

Please replace paragraph [0055] with the following amended paragraph:

**[0055]** Fig. 7 is a disassembled perspective view of an alternative embodiment of the wafer support of Figs. 1 and 2 that employs a segmented peripheral source 50 for providing the inductive element 23. Segmented peripheral ICP sources are more particularly described in copending U.S. Patent Application Serial No. \_\_\_\_\_, Express Mail No. EV354971157US, filed on even date herewith, by the inventor hereof, and hereby expressly incorporated by reference herein in its entirety. The source 50 includes a segmented antenna which forms the inductive element 23, which is mounted in a congruent insulating plate 56 that separates the inductive device 23 from the chamber wall 12 and other conductive components of the chamber. The element 23 has terminals 51,52 that may respectively connect the inductor 23 in series between the impedances 24 and 25 (not shown in Fig. 7) and the ESC 21. An annular, segmented, slotted Faraday shield 53 is provided to serve as the shield 28 over the inductor 23. An insulator 54 may be provided between the shield [[54]] 53 and the inductor 23. Otherwise, the inductor 23 of the source 50 may be connected in the various ways set forth above for the other inductor configurations. The embodiment of Fig. 7 combines the features of the integrated, electrostatic, inductively-coupled wafer support (i-ESIC) 20 and the segmented peripheral ionization source of the incorporated patent application.